

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1-24. (canceled).

25. (currently amended): A multilayer printed circuit board comprising:
a resin substrate board having, on both sides thereof, first resin insulating layers each
comprised of the same resin material;
a lower metal layer, having a conductor circuit having the same pattern as said lower
metal layer, on each of said first resin insulating layers; and
wherein
said resin insulating layers comprise thermosetting polyolefin resin;
said lower metal layers are composed of at least one metal selected from among the
group consisting of metals (exclusive of Cu) of the 4th through 7th periods in Group 4A through
Group 1B of the long-form periodic table of the elements, Al, and Sn;
said conductor circuit comprises a metal; and
each of said first resin insulating layers has a flat and level surface.

26. (currently amended): The multilayer printed circuit board according to Claim 25

wherein each of said lower metal layers is a layer containing at least one metal selected from among the group consisting of Al, Fe, W, Mo, Sn, Ni, Co, Cr, Ti and noble metals.

27-28. (canceled).

29. (previously presented): The multilayer printed circuit board according to Claim 25

wherein each of said first resin insulating layers has a surface obtained by plasma treatment or corona discharge treatment.

30. (currently amended): The multilayer printed circuit board according to Claim 25
wherein

each of said conductor circuits has an upper metal layer on its surface;

wherein said upper metal layer is composed of at least one metal selected from among the group consisting of metals (exclusive of Cu) of the 4th through 7th periods in Group 4A through Group 1B of the long-form periodic table of the elements, Al, and Sn; and
said upper metal layer has a second resin insulating layer or a solder resist layer thereon.

31. (previously presented): The multilayer printed circuit board according to Claim 25

wherein each of said lower metal layers on the surface of said first resin insulating layers has a Cu layer formed on its surface, and

said conductor circuit is constructed on said Cu layer.

32. (previously presented): The multilayer printed circuit board according to Claim
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wherein the thickness of each of said lower metal layers is 0.01 to 0.2 μm .

33-63. (canceled).

64. (previously presented): The multilayer printed circuit board according to Claim
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wherein each of said lower metal layers is formed by plating, physical vapor deposition
or chemical vapor deposition.

65. (previously presented): The multilayer printed circuit board according to Claim
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wherein said thermosetting polyolefin resin has a dielectric constant value of not more
than 3 and a dielectric loss tangent value of not more than 0.05.

66. (canceled).

67. (previously presented): The multilayer printed circuit board according to Claim
25 comprising a successive series of units, each unit comprising the first resin insulating layer,

the lower metal layer on said first resin insulating layer and the conductor circuit on said lower metal layer.

68. (previously presented): The multilayer printed circuit board according to Claim 30 comprising, on said second resin insulating layer, another lower metal layer on said second resin insulating layer, and another conductor circuit made of metal on said another lower metal layer.

69. (new): The multilayer printed circuit board according to Claim 25, wherein said resin substrate board is a copper-clad laminate, and has a buildup structure on each side.

70. (new): The multilayer printed circuit board according to Claim 30, wherein said upper metal layer is formed on the whole surface of said conductor circuit.